



# COM-HPC™ INTERCONNECT SOLUTIONS

## 0.635 mm PITCH HIGH-SPEED, HIGH-DENSITY SYSTEM

Samtec offers a high-density interconnect system that meets the COM-HPC™ standard for high-performance Computer-on-Modules. COM-HPC™ meets the growing demands for embedded systems to provide ultra-high speed performance and extended connectivity with limitless scalability.

# COM+HPC™

### HIGH-SPEED PERFORMANCE

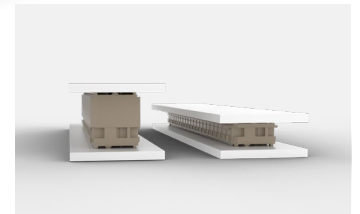
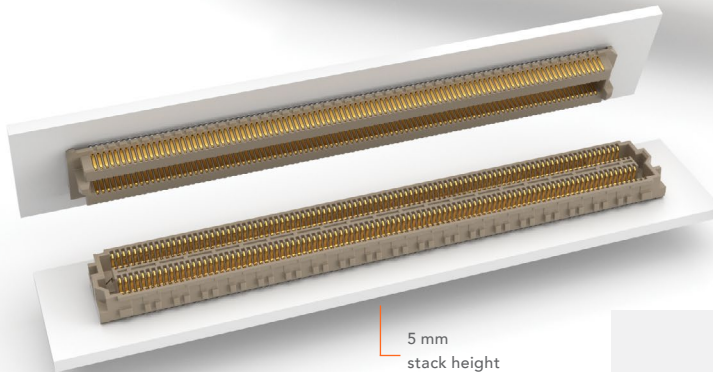
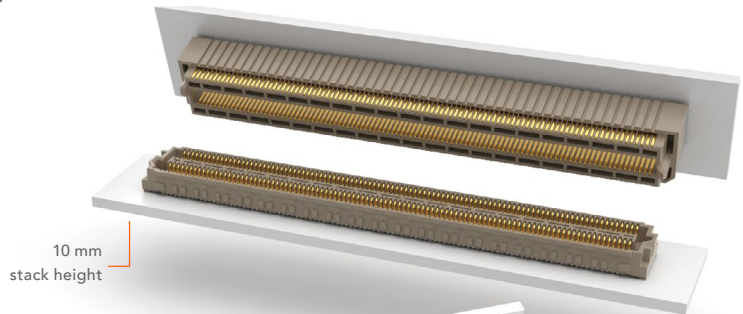
- Up to 32 Gbps per channel
  - 4096 Gbps max aggregate
  - 2088 Gbps per square inch
- PCIe® Gen 4/5 compliant
- 10 G/25 G Ethernet compliant
- Up to 300 W at 11.4 – 12.6 Volts

### HIGH-DENSITY DESIGN

- High pin count interconnect system
  - 400 total pins
  - 4 x 100 design
- 0.635 mm pitch
  - Row 1 to row 2: 2.2 mm
  - Row 2 to row 3: 2.4 mm
  - Row 3 to row 4: 2.2 mm

### APPLICATIONS

- Datacom & Telecom
- Embedded Edge Servers
- Industrial
- Medical Imaging
- 5G Wireless Infrastructure
- 5G Connected Vehicles



5 mm and 10 mm stack heights

### System

- ASP-209946-01 (Female) / ASP-214802-01 (Male) – 5 mm Stack Height COM-HPC™ Interconnects
- ASP-209946-01 (Female) / ASP-209948-01 (Male) – 10 mm Stack Height COM-HPC™ Interconnects

For more information, please contact [standards@samtec.com](mailto:standards@samtec.com)